



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



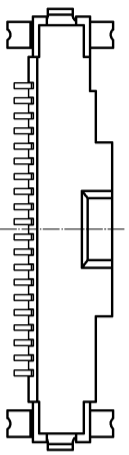
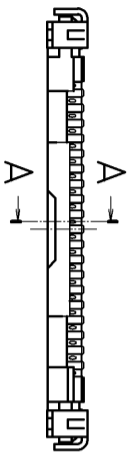
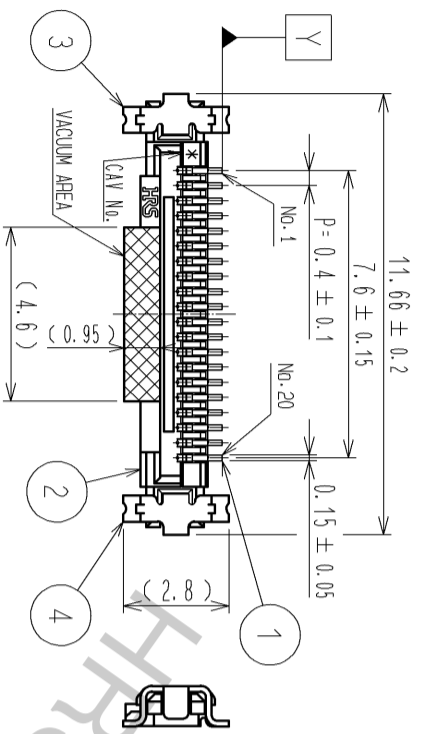
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

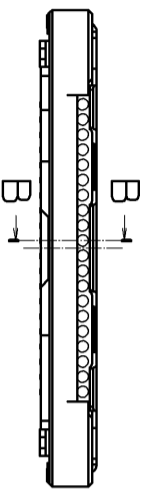
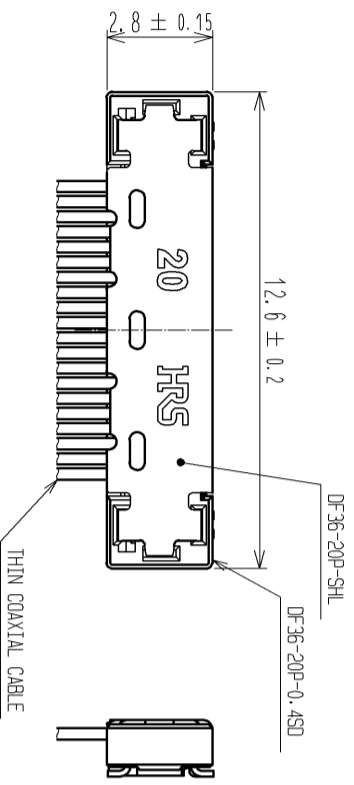
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

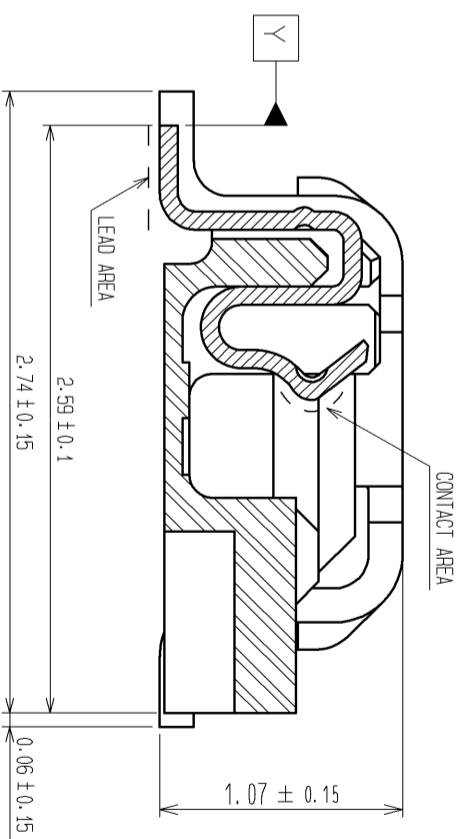




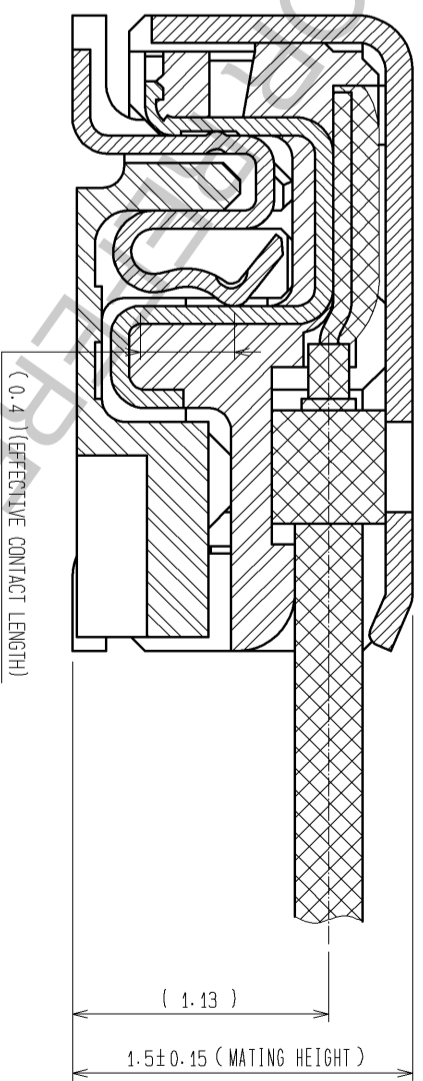
MATING FIGURE



A-A (FREE)



B-B (FREE)



- NOTES
1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX.
 2. STIFFENER IS REQUIRED FOR MOUNTING ONTO FPC IN ORDER TO AVOID STRESS BY FPC SLACKING TO MOUNTED CONNECTOR.
 3. UNMATING SHALL BE DONE WITH THE SPECIFIC EXTRACTION TOOL.

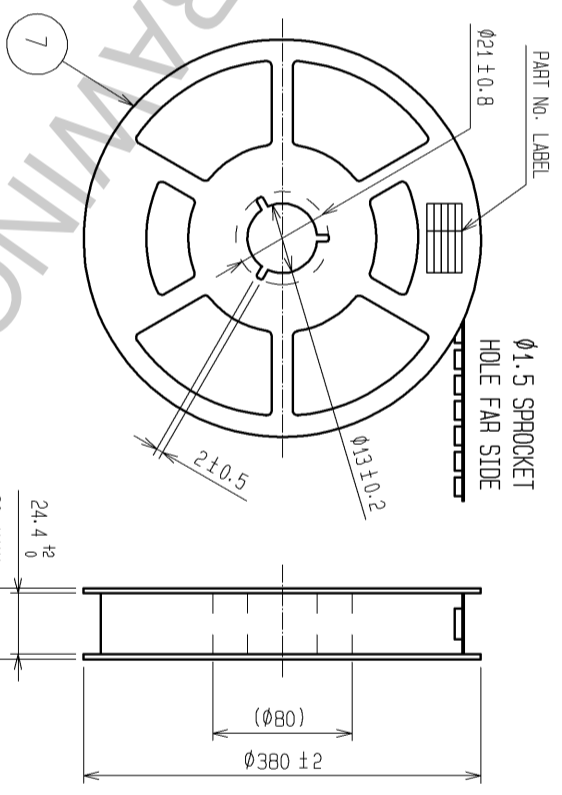
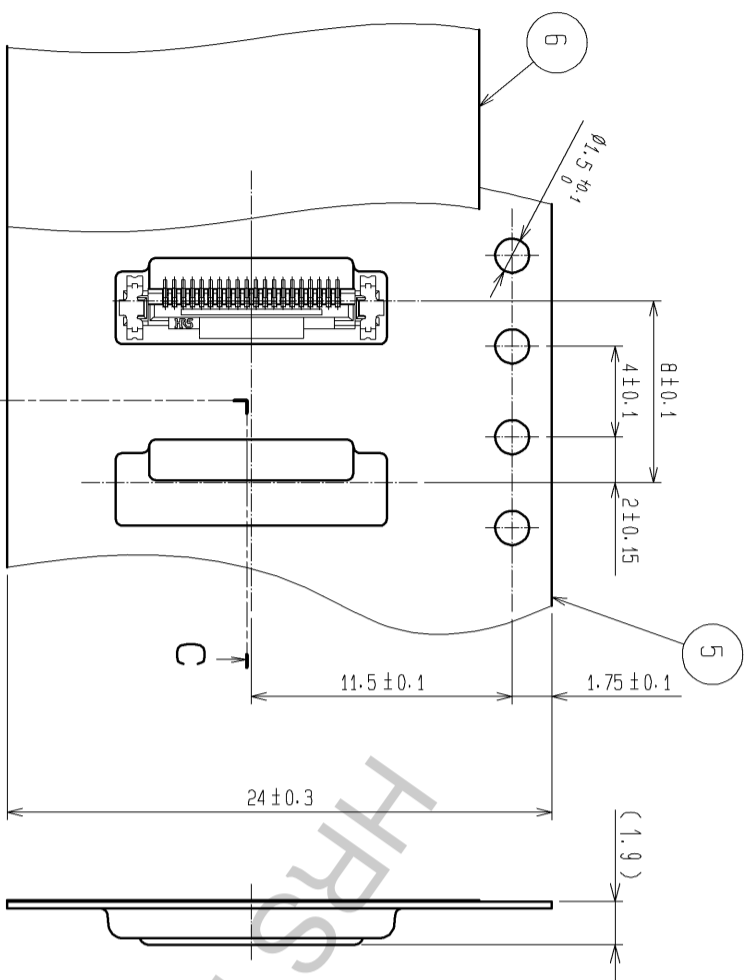
F E D C B A

FORM HCO011-5-7 1 2 3 4 5 6 7 8

NO.	1	2	3	4	5	6	7
UNITS	mm						
MATERIAL	PHOSPHOR BRONZE	LCP	PHOSPHOR BRONZE	UL94V-0 · BLACK	PS	POLYESTER	PS
FINISH							
REMARKS	CONTACT AREA : Au PLATING 0.3µm min LEAD AREA : Au PLATING 0.1µm min UNDER PLATING : Ni PLATING 2µm min		WHOLE AREA : Au PLATING 0.1µm min UNDER PLATING : Ni PLATING 2µm min				BLACK
NO.	1	2	3	4	5	6	7
MATERIAL	PHOSPHOR BRONZE			PHOSPHOR BRONZE			
FINISH							
REMARKS	WHOLE AREA : Au PLATING 0.1µm min UNDER PLATING : Ni PLATING 2µm min						CLEAR
SCALE	5 : 1						
COUNT							
DESCRIPTION OF REVISIONS							
DESIGNED	TP. MATSUOTO						
CHECKED	HS. OZAWA						
DATE	10.10.05						
APPROVED	TS. SAKATA						
DRAWING NO.	EDC3-320369-03						
PART NO.	DF36-20S-0.4V(52)						
CODE	CL662-4039-3-52						
NO.	1						
DATE							



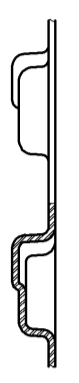
HIROSE ELECTRIC CO., LTD.



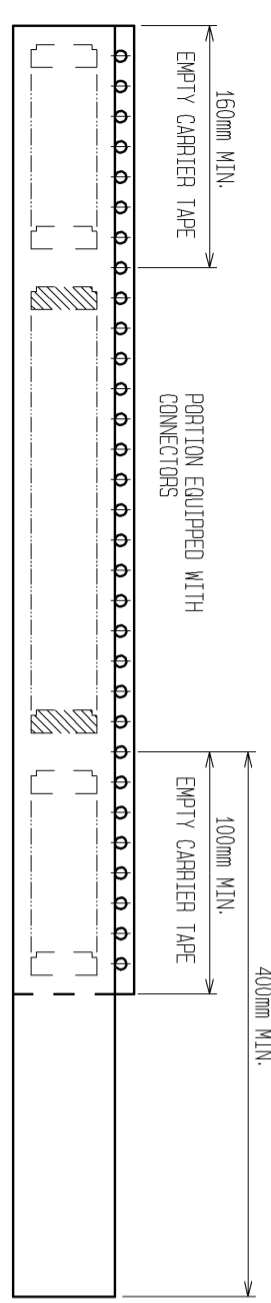
DETAIL OF PART NO. LABEL

生産日	年 月 日
製品コード	CL662-4039-3-52
製品名	DF36-20S-0.4V(52)
納入数量	5,000pcs
納入者	ヒロセ電機(株)
SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	

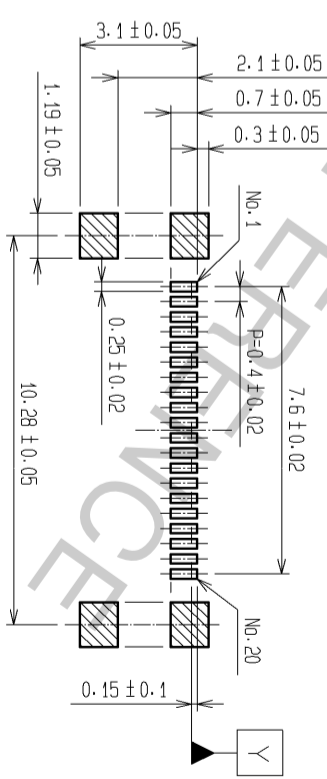
C-C(FREE)



TAPING (FREE)



RECOMMENDED PATTERN(5:1)



GROUND AREA

RECOMMENDED METAL MASK

THICKNESS: 0.1mm
OPENING RATIO: LEAD AREA 90%
GROUND AREA 90%

NOTES 4. PER REEL: 5000 COMPONENTS.
5. REFER TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

FORM HC0011-5-8

DRAWING NO.	EDC3-320369-03
PART NO.	DF36-20S-0.4V(52)
CODE NO.	CL662-4039-3-52

HR5

2/2